

# FFA60UP60DN Ultrafast Recovery Power Rectifier

### **Features**

- · High voltage and high reliability
- · High speed switching
- · Low forward voltage

### **Applications**

- · General purpose
- · Switched mode power supply
- · Free-wheeling diode for motor application
- · Power switching Circuits



1. Anode 2. Cathode 3. Anode

## Absolute Maximum Ratings (per diode) T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 80°C	30	A
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	180	А
$T_{J,}T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	°C

### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	1.03	°C/W

## **Electrical Characteristics** (per diode) T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage I <sub>F</sub> = 30A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C			2.3 2.1	V V
I <sub>RM</sub> *	Maximum Instantaneous Reverse Current @ rated V <sub>R</sub>	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C			15 150	μ <b>Α</b> μ <b>Α</b>
t <sub>rr</sub>	Maximum Reverse Recovery Time (I <sub>F</sub> = 1A, di/dt = 100A/μs)				70	nS
t <sub>rr</sub> t <sub>rr</sub> l <sub>rr</sub> Q <sub>rr</sub>	Maximum Reverse Recovery Time (I <sub>F</sub> = 30A, di/dt = 200A/μs)	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$			90 150 8 360	nS nS A nC
W <sub>AVL</sub>	Avalanche Energy (L = 40mH)	•	20			mJ

<sup>\*</sup> Pulse Test: Pulse Width =  $300\mu s$ , Duty Cycle = 2%

### **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
F60UP60DN	FFA60UP60DN	TO-3P	7.0	-	30



### **Typical Performance Characteristics**

Figure 1. Typical Forward Voltage Drop vs. Forward Current

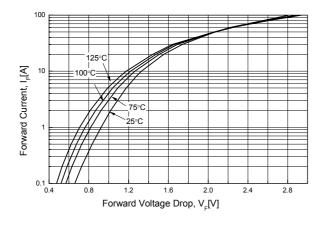


Figure 2. Typical Reverse Current vs. Reverse Voltage

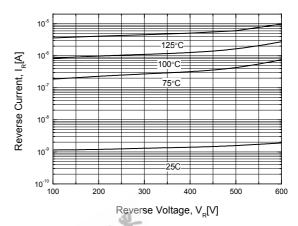


Figure 3. Typical Junction Capacitance

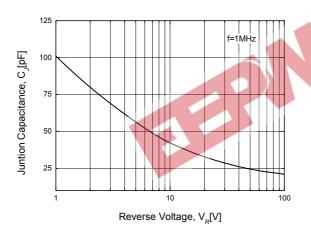


Figure 4. Typical Reverse Recovery Time vs. di/dt

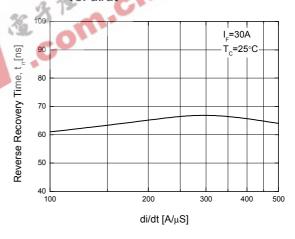


Figure 5. Typical Reverse Recovery Current vs. di/dt

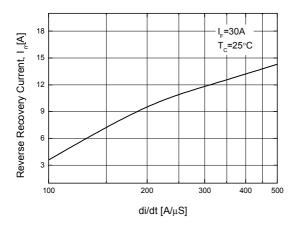
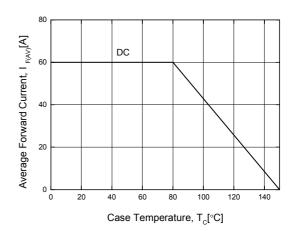


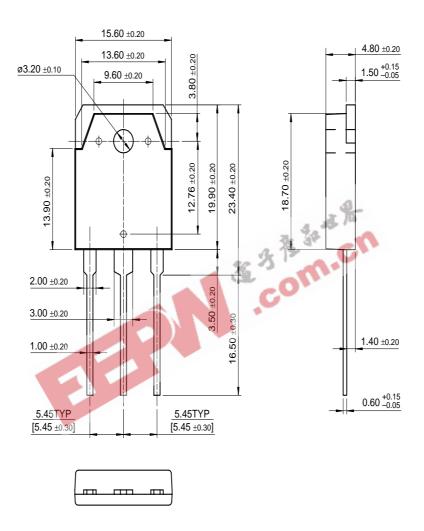
Figure 6. Forwrd Current Derating Curve



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### **Mechanical Dimensions**

# TO-3P



Dimensions in Millimeters

4

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